

## ● General Description

The AGM3404E combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

## ● Features

- Advance high cell density Trench technology

- Low  $R_{DS(ON)}$  to minimize conductive loss

- Low Gate Charge for fast switching

- Low Thermal resistance

## ● Application

- MB/VGA Vcore

- SMPS 2<sup>nd</sup> Synchronous Rectifier

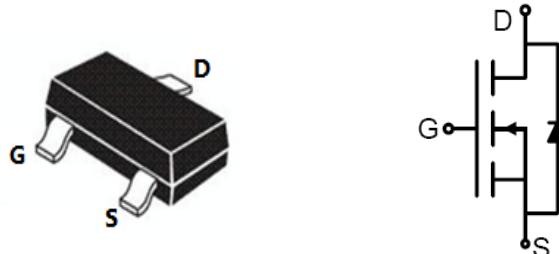
- POL application

- BLDC Motor driver

## Product Summary

BVDSS	RDS(on)	ID
30V	17mΩ	5.6A

## SOT-23-3 Pin Configuration



## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3404E	AGM3404E	SOT-23-3	----	----	3000

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	30	V
VGS	Gate-Source Voltage (VDS=0V)	±12	V
ID	Drain Current-Continuous(TA=25°C) <b>(Note 1)</b>	5.6	A
	Drain Current-Continuous(TA=70°C)	4.5	A
IDM (pulse)	Drain Current-Continuous@ Current-Pulsed <b>(Note 2)</b>	30	A
PD	Maximum Power Dissipation(TA=25°C)	1.2	W
	Maximum Power Dissipation(TA=70°C)	0.8	W
EAS	Avalanche energy <b>(Note 3)</b>	--	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	104	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	--	°C/W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=30V, VGS=0V	--	--	1	µA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250µA	1.0	1.5	2.2	V
gFS	Forward Transconductance	VDS=5V, ID=5.6A	--	--	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=5.6A	--	17	24	mΩ
		VGS=4.5V, ID=5.0A	--	26	38	mΩ
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=15V, VGS=0V, F=1MHZ	--	526	--	pF
Coss	Output Capacitance		--	78	--	pF
Crss	Reverse Transfer Capacitance		--	69	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V, f=1.0MHz	--	--	--	Ω
<b>Switching Times</b>						
td(on)	Turn-on Delay Time	VGS=10V, VDS=15V, RGEN=3Ω, ID=5.6A	--	5.0	--	nS
tr	Turn-on Rise Time		--	28	--	nS
td(off)	Turn-Off Delay Time		--	13	--	nS
tf	Turn-Off Fall Time		--	22	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=15V, ID=5.6A	--	12	--	nC
Qgs	Gate-Source Charge		--	2.4	--	nC
Qgd	Gate-Drain Charge		--	2.3	--	nC
<b>Source-Drain Diode Characteristics</b>						
ISD	Source-Drain Current(Body Diode)		--	--	5.6	A
VSD	Forward on Voltage	VGS=0V, IS=5.6A	--	--	1.2	V
trr	Reverse Recovery Time	IF=5.6A , dI/dt=100A/µs , TJ=25°C	--	1.3	--	ns
Qrr	Reverse Recovery Charge		--	17	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

## ■ Typical Performance Characteristics

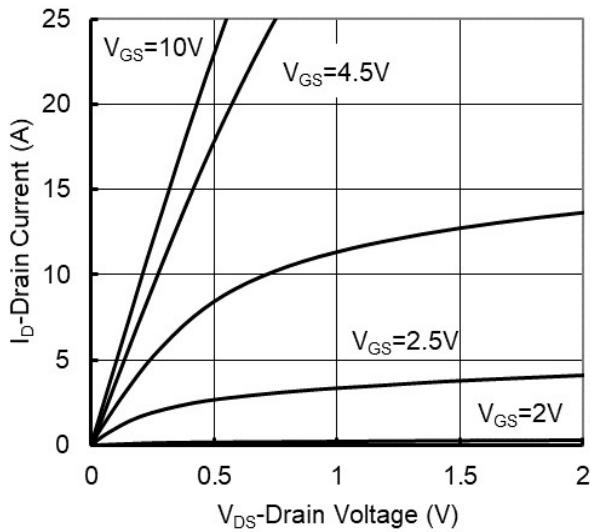


Figure 1. Output Characteristics

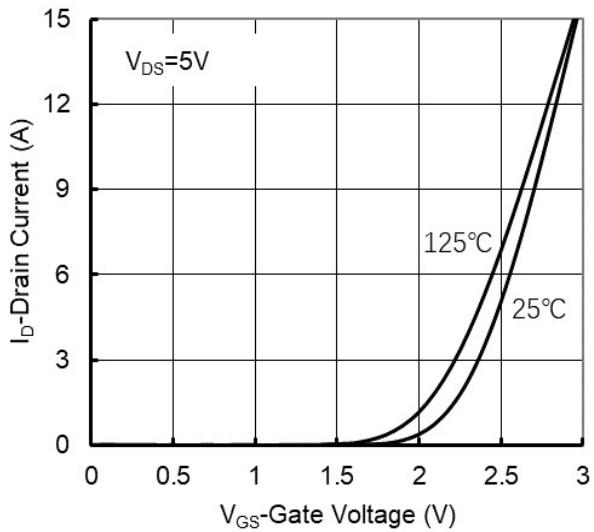


Figure 2. Transfer Characteristics

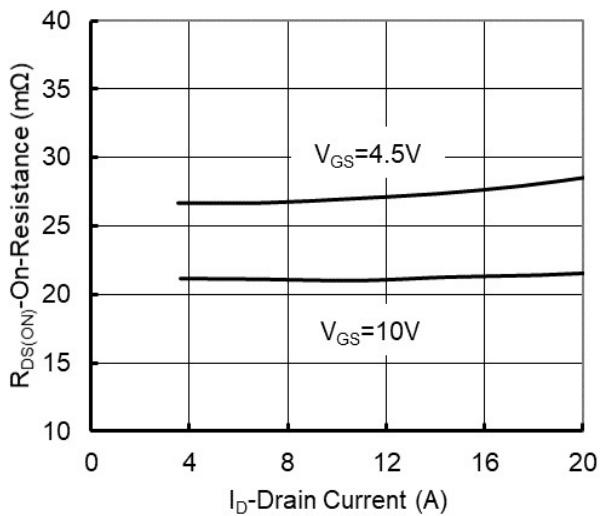


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

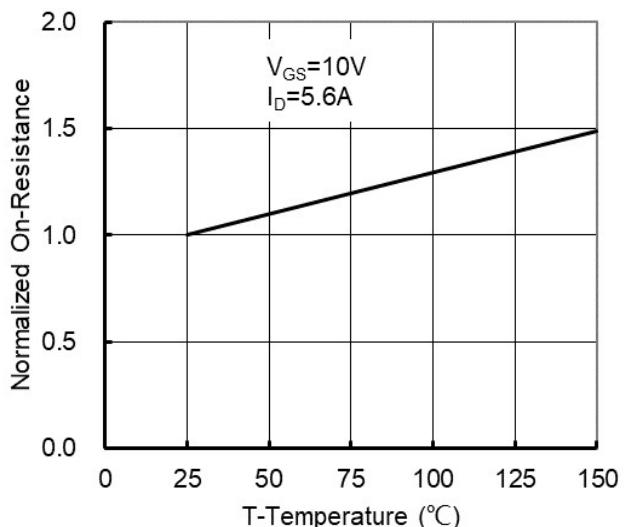


Figure 4: On-Resistance vs. Junction Temperature

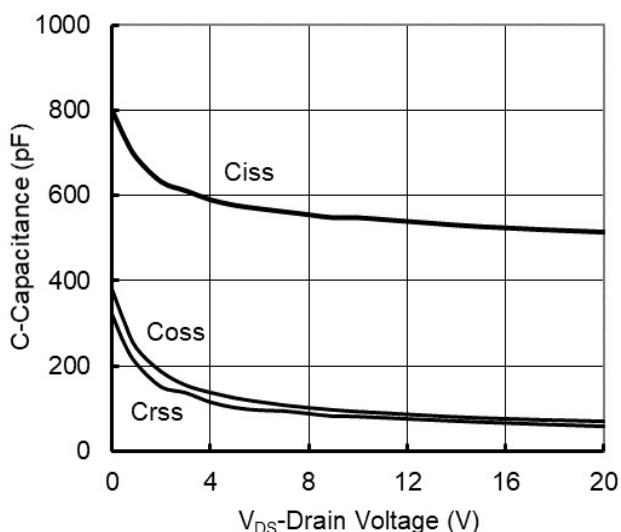


Figure 5. Capacitance Characteristics

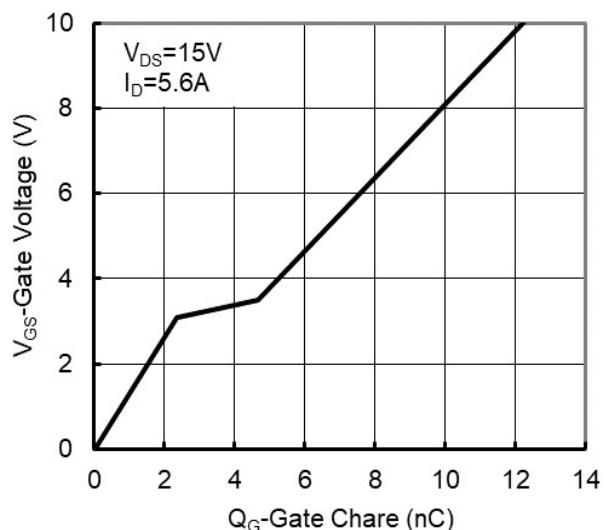
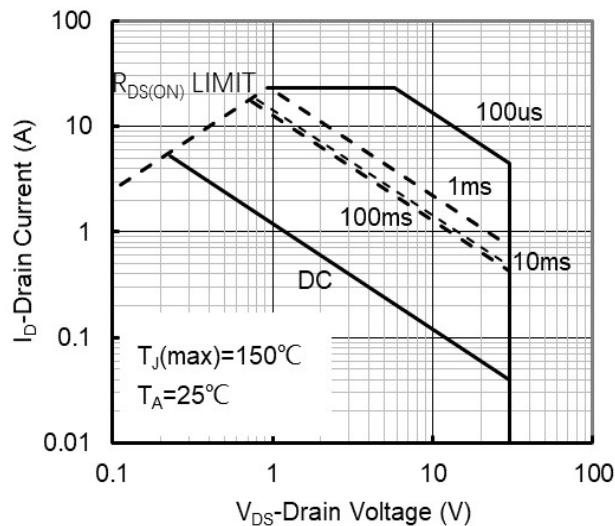
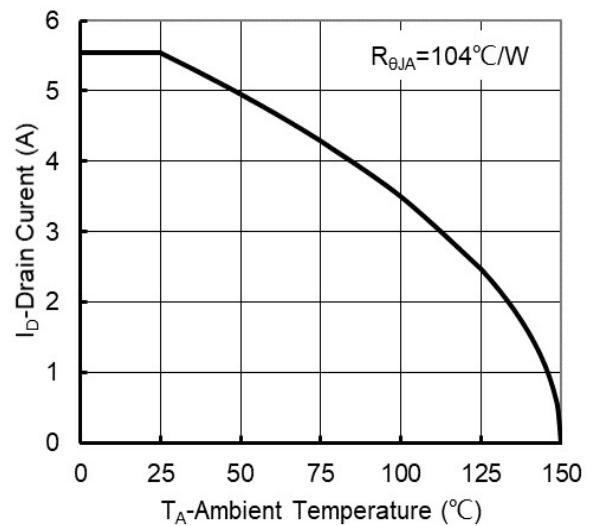
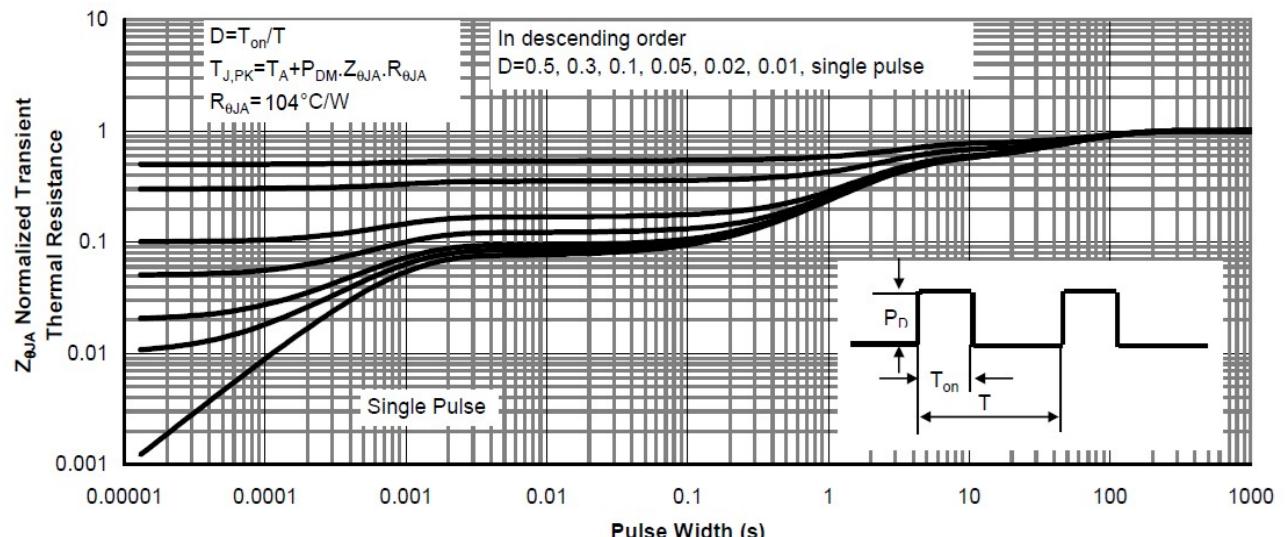
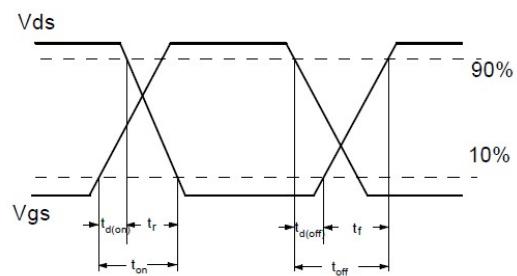
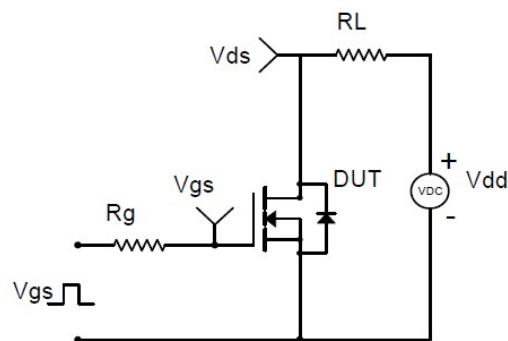
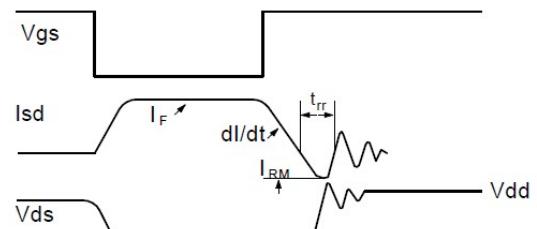
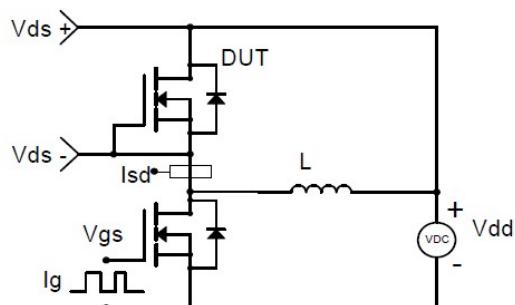
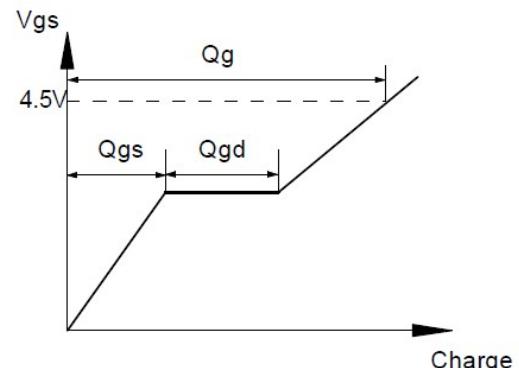
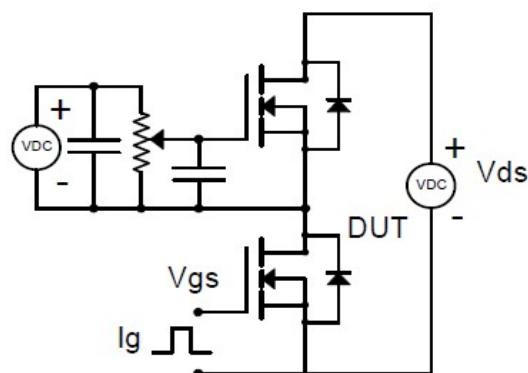
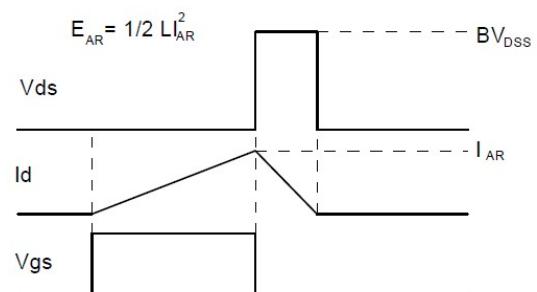
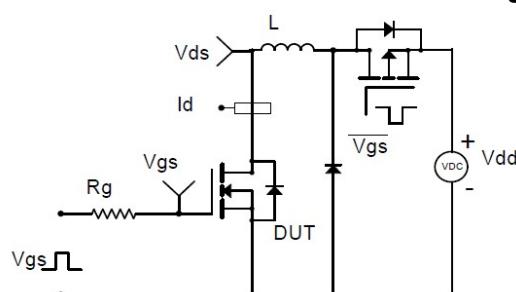
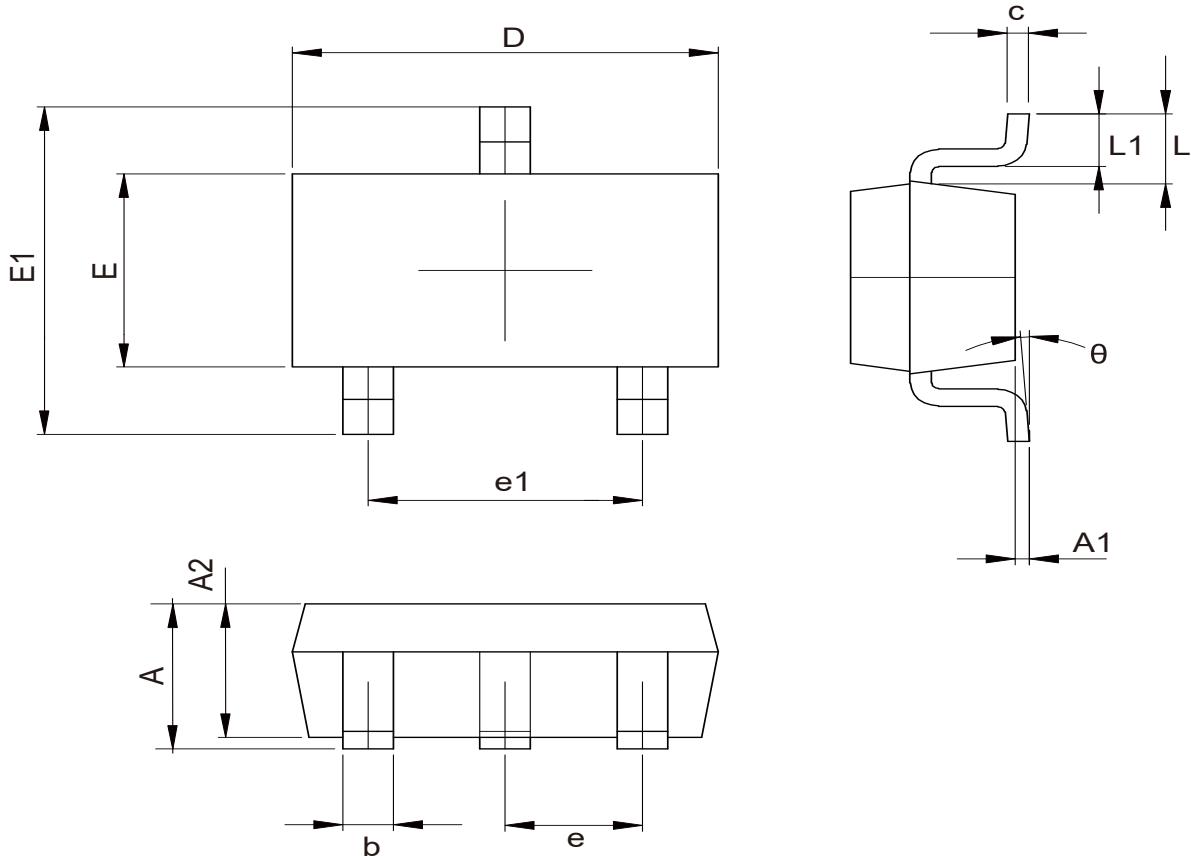


Figure 6. Gate Charge


**Figure7. Safe Operation Area**

**Figure8. Maximum Continuous Drain Current vs Ambient Temperature**

**Figure9. Normalized Maximum Transient Thermal Impedance**


**Resistive Switching Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**

**Gate Charge Test Circuit & Waveform**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

**SOT-23-3L**  
PACKAGE OUTLINE DIMENSIONS



COMMON DIMENSIONS CUNITS MEASURE=MILLIMETER			
SYMBOL	MIN	NOM	MAX
A	1.050	—	1.300
A1	0.000	—	0.200
A2	1.050	—	1.200
b	0.300	0.400	0.500
c	0.100	—	0.200
D	2.820	2.900	3.020
E	1.500	1.600	1.700
E1	2.650	2.800	2.950
e	0.950TYP		
e1	1.800	1.900	2.000
L	0.6REF		
L1	0.300	0.450	0.600
θ	0°	--	8°

Unit:mm

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